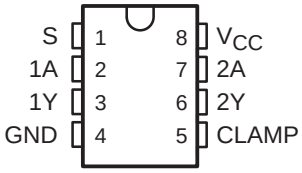
- **Characterized for Use to 300 mA**
- **No Output Latch-Up at 55 V (After Conducting 300 mA)**
- **High-Voltage Outputs (100 V Typ)**
- **Output Clamp Diodes for Transient Suppression (300 mA, 70 V)**
- **TTL- or MOS-Compatible Diode-Clamped Inputs**
- **pnp Transistor Inputs Reduce Input Current**
- **Standard Supply Voltage**
- **Suitable for Hammer-Driver Applications**
- **Plastic DIP (P) With Copper-Lead Frame Provides Cooler Operation and Improved Reliability**

D OR P PACKAGE
(TOP VIEW)

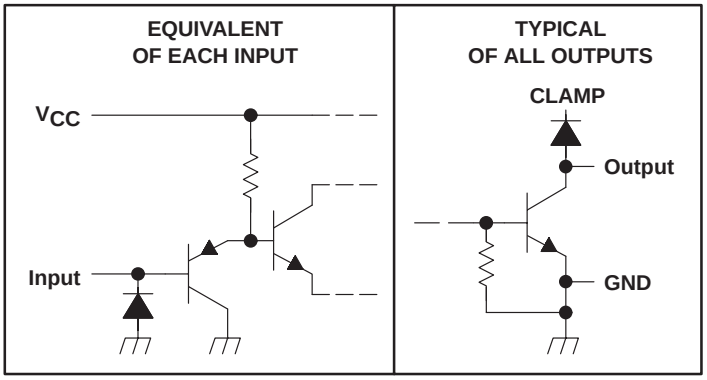


description

The SN75476 through SN75478 are dual peripheral drivers designed for use in systems that require high current, high voltage, and fast switching times. The SN75476, SN75477, and SN75478 provide AND, NAND, and OR drivers respectively. These devices have diode-clamped inputs as well as high-current, high-voltage clamp diodes on the outputs for inductive transient protection.

The SN75476, SN75477, and SN75478 drivers are characterized for operation from 0°C to 70°C.

schematics of inputs and outputs



Function Tables

SN75476
(each AND driver)

INPUTS		OUTPUT
A	S	Y
H	H	H
L	X	L
X	L	L

SN75477
(each NAND driver)

INPUTS		OUTPUT
A	S	Y
H	H	L
L	X	H
X	L	H

SN75478
(each OR driver)

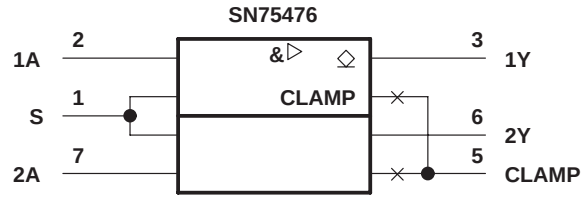
INPUTS		OUTPUT
A	S	Y
H	X	H
X	H	H
L	L	L

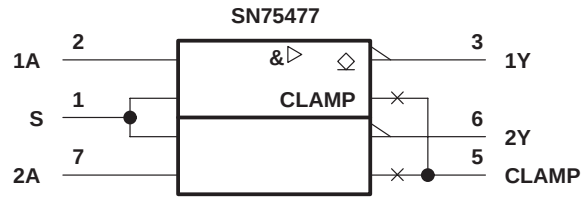
H = high level, L = low level
X = irrelevant

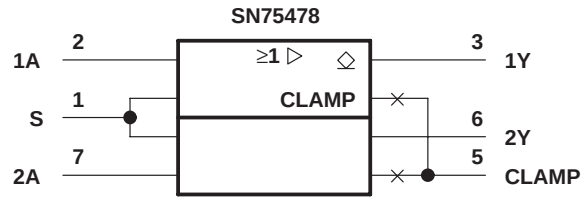
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic symbols†

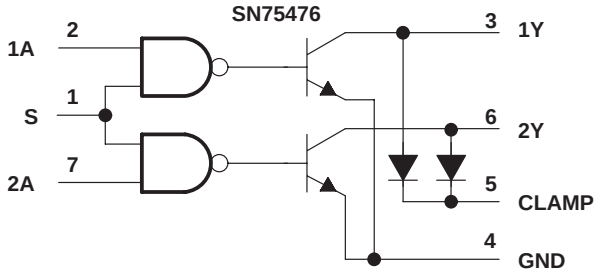




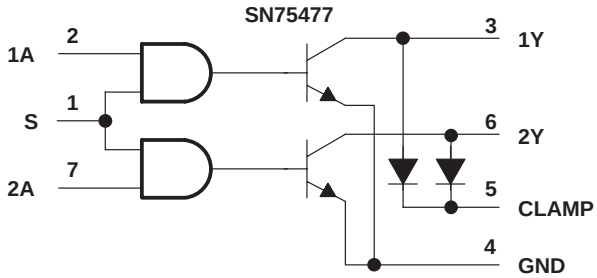


† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

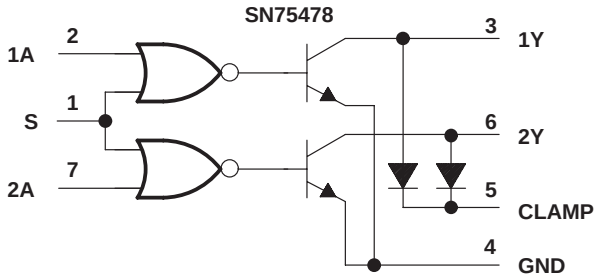
logic diagrams (positive logic)



Positive Logic: $Y = AS$ or $\overline{\overline{A}+\overline{S}}$



Positive Logic: $Y = \overline{AS}$ or $\overline{A}+\overline{S}$



Positive Logic: $Y = A+S$ or $\overline{\overline{A}\,\overline{S}}$

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage, V_I . . . . . 5.5 V
Continuous output current (see Note 2) . . . . . 400 mA
Peak output current: $t_w \leq 10$ ms, duty cycle $\leq 50\%$ . . . . . 500 mA
$t_w \leq 30$ ns, duty cycle $\leq 0.002\%$ . . . . . 3 A
Output clamp current, I_{OK} . . . . . 400 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

NOTES: 1. Voltage values are with respect to network GND.
2. Both halves of this dual circuit may conduct rated current simultaneously; however, power dissipation averaged over a short time interval must fall within the continuous power dissipation ratings.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW
P	1000 mW	8.0 mW/°C	640 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.5	5	5.5	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
Operating free-air temperature, T_A	0		70	°C

electrical characteristics over recommended operating free-air temperature range

PARAMETER			TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	Input clamp voltage		I_I = –12 mA			–0.95	–1.5	V
V_{OL}	Low-level output voltage		V_{CC} = 4.5 V, V_{IH} = 2 V, V_{IL} = 0.8 V	I_{OL} = 100 mA		0.16	0.3	V
				I_{OL} = 175 mA		0.22	0.5	
				I_{OL} = 300 mA		0.33	0.6	
$V_{O(BR)}$	Output breakdown voltage		V_{CC} = 4.5 V,	I_{OH} = 100 μA	70	100		V
$V_{R(K)}$	Output clamp reverse voltage		V_{CC} = 4.5 V,	I_R = 100 μA	70	100		V
$V_{F(K)}$	Output clamp forward voltage		V_{CC} = 4.5 V,	I_F = 300 mA	0.8	1.15	1.6	V
I_{OH}	High-level output current		V_{CC} = 4.5 V, V_{IL} = 0.8 V,	V_{IH} = 2 V, V_{OH} = 70 V		1	100	μA
I_{IH}	High-level input current		V_{CC} = 5.5 V,	V_I = 5.5 V		0.01	10	μA
I_{IL}	Low-level input current	A input	V_{CC} = 5.5 V,	V_I = 0.8 V		–80	–110	μA
		S input				–160	–220	
I_{CCH}	Supply current, outputs high	SN75476	V_{CC} = 5.5 V	V_I = 5 V		10	17	mA
		SN75477		V_I = 0		10	17	
		SN75478		V_I = 5 V		10	17	
I_{CCL}	Supply current, outputs low	SN75476	V_{CC} = 5.5 V	V_I = 0		54	75	mA
		SN75477		V_I = 5 V		54	75	
		SN75478		V_I = 0		54	75	

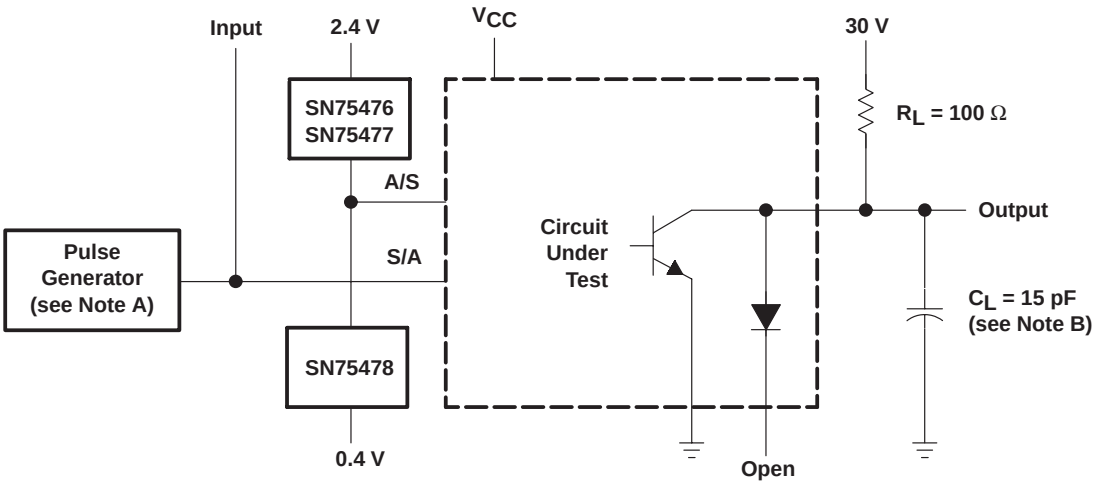
† All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

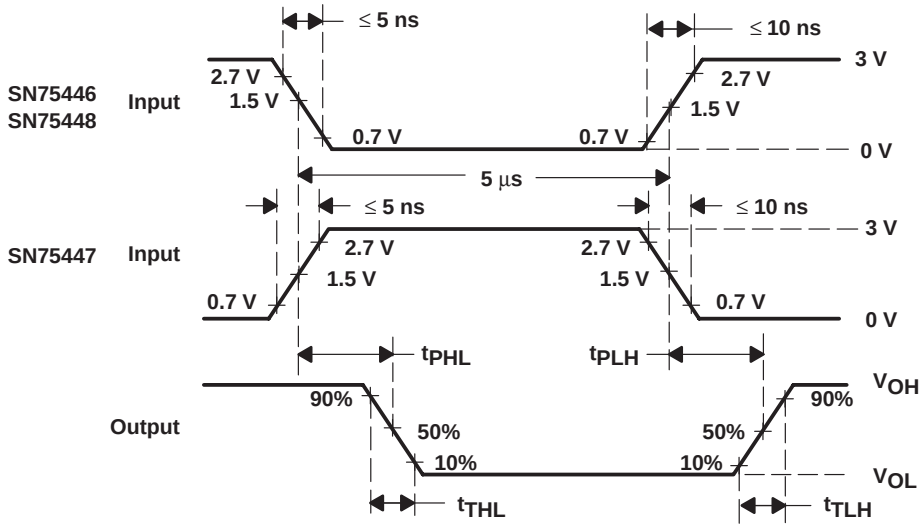
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	C_L = 15 pF, See Figure 1	R_L = 100 Ω,		200	350	ns
t_{PHL}	Propagation delay time, high-to-low-level output				200	350	ns
t_{TLH}	Transition time, low-to-high-level output				50	125	ns
t_{THL}	Transition time, high-to-low-level output				90	125	ns
V_{OH}	High-level output voltage after switching	V_S = 55 V, See Figure 2	I_O ≈ 300 mA,	V_S–18			mV

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251–1443

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

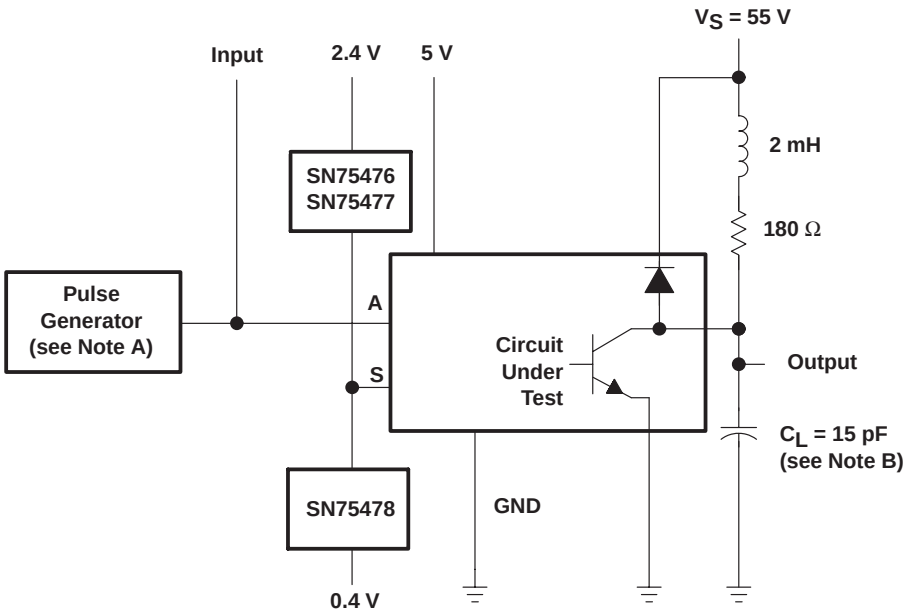


VOLTAGE WAVEFORMS

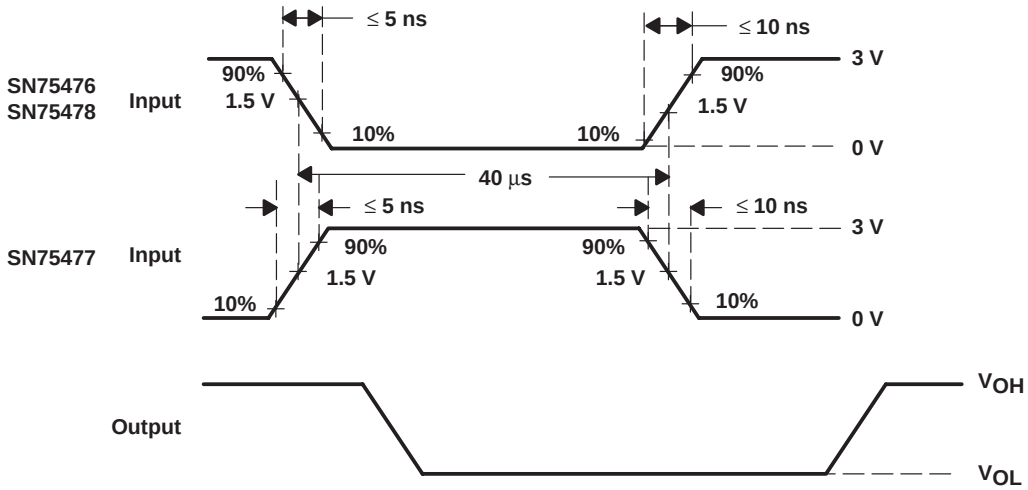
NOTES: A. The pulse generator has the following characteristics: PRR = 100 kHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms, Switching Characteristics

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 2. Latch-Up Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN75477D	Active	Production	SOIC (D) | 8	75 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477
SN75477D.A	Active	Production	SOIC (D) | 8	75 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477
SN75477DE4	Active	Production	SOIC (D) | 8	75 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477
SN75477DR	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477
SN75477DR.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477
SN75477DRE4	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477
SN75477P	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75477P
SN75477P.A	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75477P
SN75477PE4	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75477P
SN75478P	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75478P
SN75478P.A	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75478P

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

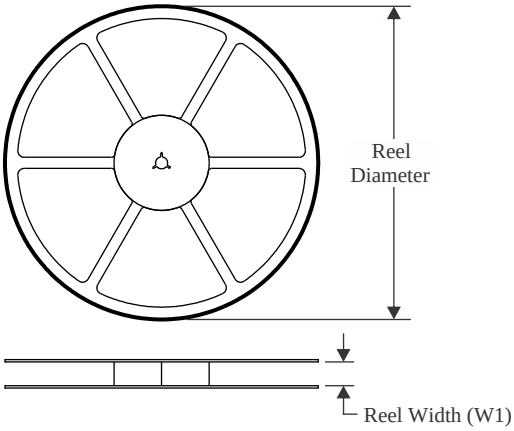
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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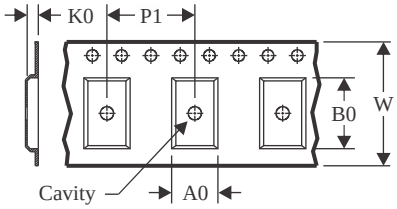
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

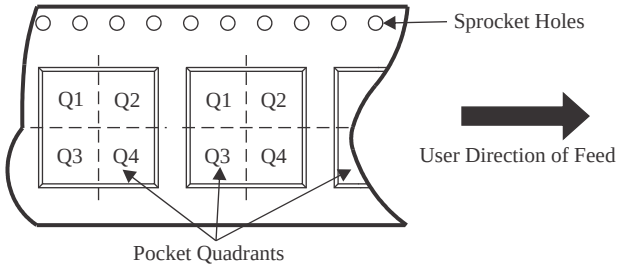


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

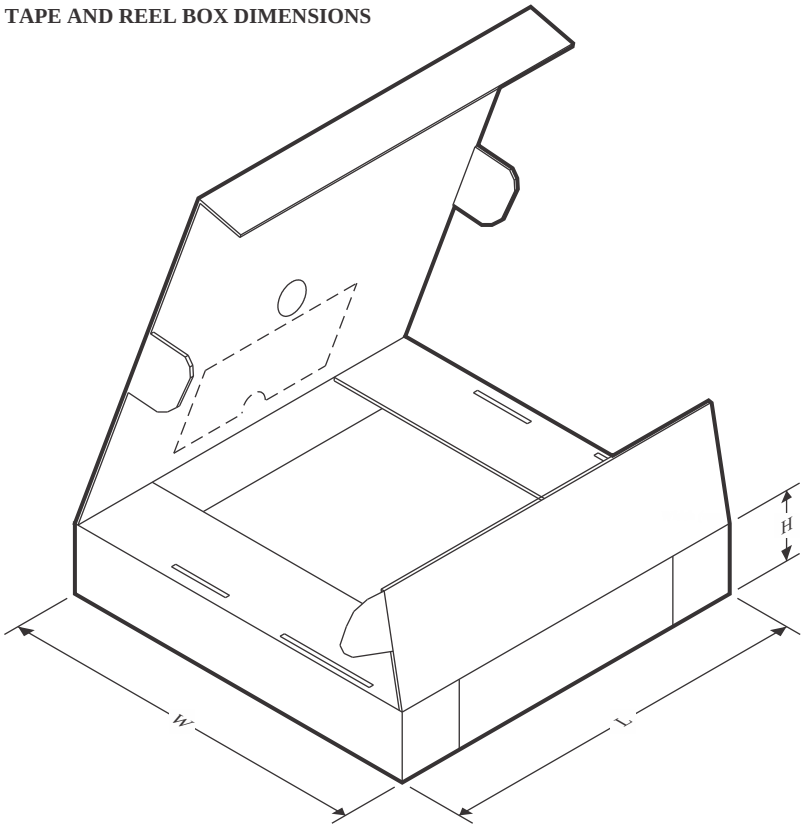
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75477DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

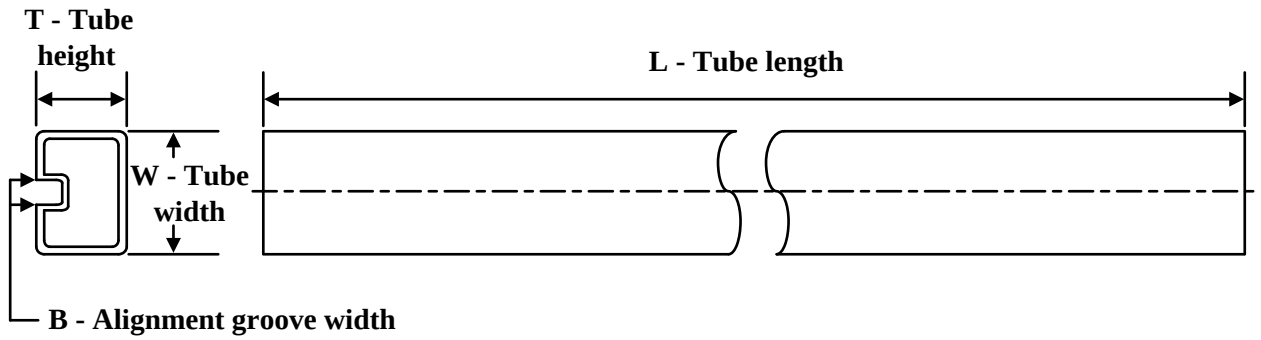
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

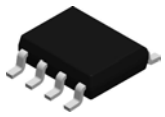
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75477DR	SOIC	D	8	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75477D	D	SOIC	8	75	507	8	3940	4.32
SN75477D.A	D	SOIC	8	75	507	8	3940	4.32
SN75477DE4	D	SOIC	8	75	507	8	3940	4.32
SN75477P	P	PDIP	8	50	506	13.97	11230	4.32
SN75477P.A	P	PDIP	8	50	506	13.97	11230	4.32
SN75477PE4	P	PDIP	8	50	506	13.97	11230	4.32
SN75478P	P	PDIP	8	50	506	13.97	11230	4.32
SN75478P.A	P	PDIP	8	50	506	13.97	11230	4.32

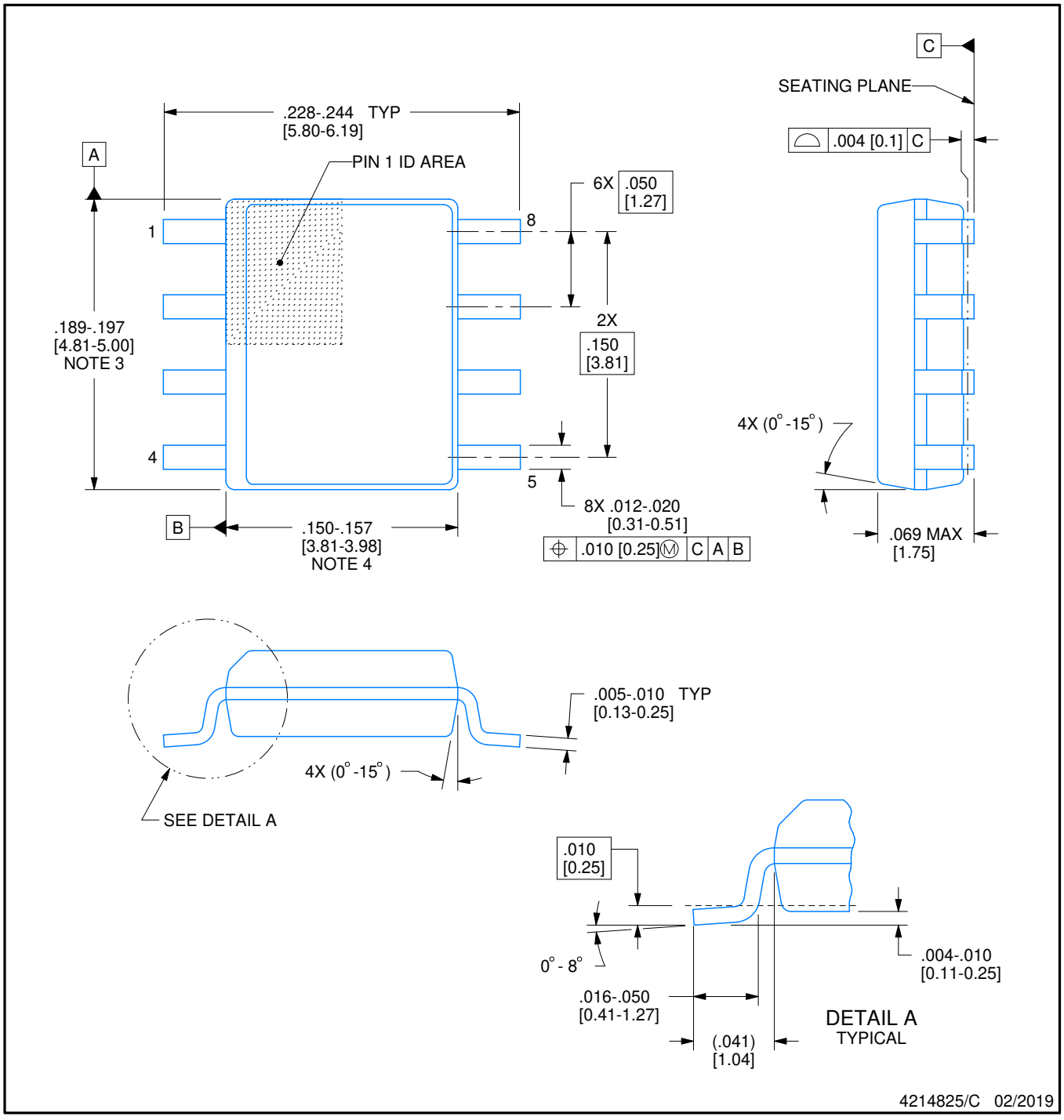


PACKAGE OUTLINE

D0008A

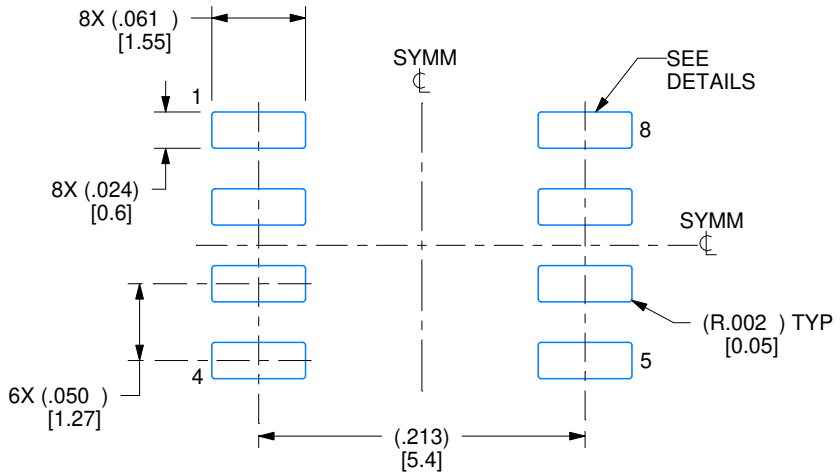
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

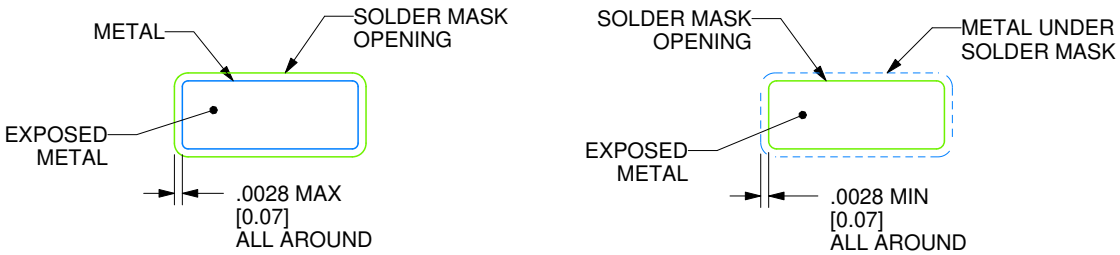


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

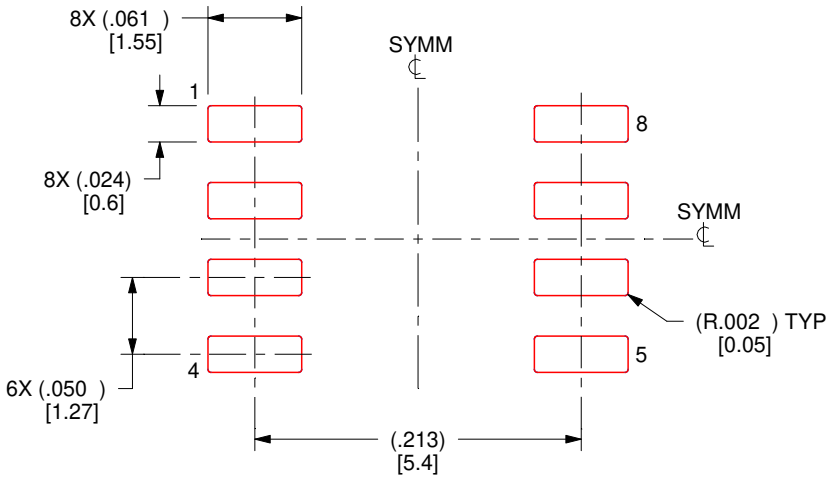
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



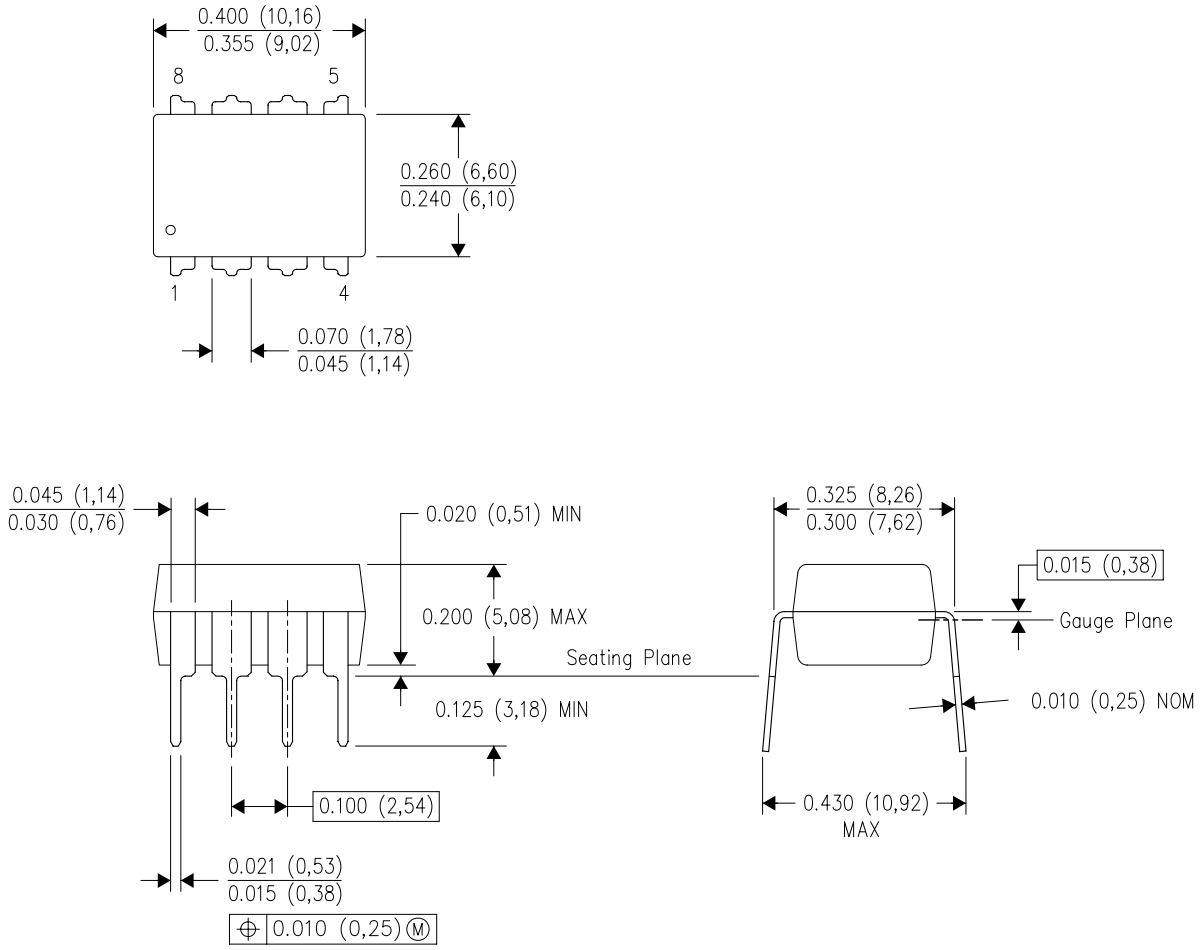
SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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